L Number	Hits	Search Text	DB	Time stamp
1	165631	(stacking stacked stack stackable mounting mounted mounting) with (die chip dice ic (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/03/17 08:38
2	512643	(heat with (spreader sink metal slug radiate cooling))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/03/17 08:59
3	7618	<pre>((stacking stacked stack stackable mounting mounted mounting) with (die chip dice ic (integrated adj circuit))) same ((heat with (spreader sink metal slug radiate cooling)))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/03/17 08:44
4	1501	<pre>(((stacking stacked stack stackable mounting mounted mounting) with (die chip dice ic (integrated adj circuit))) same ((heat with (spreader sink metal slug radiate cooling)))) and (thermal with expansion)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 09:00
5	987	(epoxy molding encapsulate encapsulation encapsulated) and ((((stacking stacked stack stackable mounting mounted mounting) with (die chip dice ic (integrated adj circuit))) same ((heat with (spreader sink metal slug radiate cooling))) and (thermal with expansion))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 . 09:02
6	941	<pre>(substrate carrier board) and ((epoxy molding encapsulate encapsulation encapsulated) and ((((stacking stacked stack stackable mounting mounted mounting) with (die chip dice ic (integrated adj circuit))) same ((heat with (spreader sink metal slug radiate cooling)))) and (thermal with expansion)))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17
7	544878	(heat with (spreader dissipating dissipated dissipate sink metal slug radiate cooling))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/03/17 09:00
8	60483	((heat with (spreader dissipating dissipated dissipate sink metal slug radiate cooling))) and (cte (thermal with expansion) coefficient)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/03/17 09:01
9	5722	<pre>(((heat with (spreader dissipating dissipated dissipate sink metal slug radiate cooling))) and (cte (thermal with expansion) coefficient)) and ((stacking stacked stack stackable mounting mounted mounting) with (die chip dice ic (integrated adj circuit)))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 09:01
10	5142	(substrate carrier board) and ((((heat with (spreader dissipating dissipated dissipate sink metal slug radiate cooling))) and (cte (thermal with expansion) coefficient)) and ((stacking stacked stack stackable mounting mounted mounting) with (die chip dice ic (integrated adj circuit))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 09:02

11	2450		T	10004/00/05
11	3450	(epoxy molding encapsulate encapsulation	USPAT;	2004/03/17
		encapsulated) and ((substrate carrier	US-PGPUB;	09:02
		board) and (((heat with (spreader	EPO; JPO;	
	1	dissipating dissipated dissipate sink	DERWENT;	
		metal slug radiate cooling))) and (cte	IBM_TDB	
		(thermal with expansion) coefficient))		
		and ((stacking stacked stack stackable	i	
		mounting mounted mounting) with (die chip		
		dice ic (integrated adj circuit)))))		
12	2837	((epoxy molding encapsulate encapsulation	USPAT;	2004/03/17
1		encapsulated) and ((substrate carrier	US-PGPUB;	09:04
1		board) and ((((heat with (spreader	EPO; JPO;	1
		dissipating dissipated dissipate sink	DERWENT;	
i		metal slug radiate cooling))) and (cte	IBM_TDB	
		(thermal with expansion) coefficient))		
		and ((stacking stacked stack stackable		
ļ		mounting mounted mounting) with (die chip		
		dice ic (integrated adj circuit))))) and		
		(package packaged packaging)		
13	2009	(((-F)	USPAT;	2004/03/17
		encapsulation encapsulated) and	US-PGPUB;	09:06
		((substrate carrier board) and (((heat	EPO; JPO;	
		with (spreader dissipating dissipated	DERWENT;	
		dissipate sink metal slug radiate	IBM_TDB	
		cooling))) and (cte (thermal with	_]
		expansion) coefficient)) and ((stacking		1
		stacked stack stackable mounting mounted		
		mounting) with (die chip dice ic		
		(integrated adj circuit)))))) and		
		(package packaged packaging)) not		
		((substrate carrier board) and ((epoxy		
		molding encapsulate encapsulation		
		encapsulated) and ((((stacking stacked		
		stack stackable mounting mounted		
		mounting) with (die chip dice ic		
		(integrated adj circuit))) same ((heat		
		with (spreader sink metal slug radiate		
		cooling)))) and (thermal with		
		expansion))))		

L Number	Hits	Search Text	DB	Time stamp
1	165631	(stacking stacked stack stackable mounting mounted mounting) with (die chip dice ic (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/03/17 08:38
2	512643	(heat with (spreader sink metal slug radiate cooling))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/03/17 08:59
3	7618	<pre>((stacking stacked stack stackable mounting mounted mounting) with (die chip dice ic (integrated adj circuit))) same ((heat with (spreader sink metal slug radiate cooling)))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/03/17 08:44
4	1501	<pre>(((stacking stacked stack stackable mounting mounted mounting) with (die chip dice ic (integrated adj circuit))) same ((heat with (spreader sink metal slug radiate cooling)))) and (thermal with expansion)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17
5	987	(epoxy molding encapsulate encapsulation encapsulated) and ((((stacking stacked stack stackable mounting mounted mounting) with (die chip dice ic (integrated adj circuit))) same ((heat with (spreader sink metal slug radiate cooling))) and (thermal with expansion))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17
6	941	<pre>(substrate carrier board) and ((epoxy molding encapsulate encapsulation encapsulated) and ((((stacking stacked stack stackable mounting mounted mounting) with (die chip dice ic (integrated adj circuit))) same ((heat with (spreader sink metal slug radiate cooling)))) and (thermal with expansion)))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17
7	544878	(heat with (spreader dissipating dissipated dissipate sink metal slug radiate cooling))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/03/17 10:25
8	60483	((heat with (spreader dissipating dissipated dissipate sink metal slug radiate cooling))) and (cte (thermal with expansion) coefficient)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/03/17
9	5722	<pre>(((heat with (spreader dissipating dissipated dissipate sink metal slug radiate cooling))) and (cte (thermal with expansion) coefficient)) and ((stacking stacked stack stackable mounting mounted mounting) with (die chip dice ic (integrated adj circuit)))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 09:01
10	5142	(substrate carrier board) and ((((heat with (spreader dissipating dissipated dissipate sink metal slug radiate cooling))) and (cte (thermal with expansion) coefficient)) and ((stacking stacked stack stackable mounting mounted mounting) with (die chip dice ic (integrated adj circuit))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 09:02

11	3450	(epoxy molding encapsulate encapsulation encapsulated) and ((substrate carrier board) and (((heat with (spreader dissipating dissipated dissipate sink metal slug radiate cooling))) and (cte (thermal with expansion) coefficient)) and ((stacking stacked stack stackable mounting mounted mounting) with (die chip dice ic (integrated adj circuit)))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17
12	2837	((epoxy molding encapsulate encapsulation encapsulated) and ((substrate carrier board) and (((heat with (spreader dissipating dissipated dissipate sink metal slug radiate cooling))) and (cte (thermal with expansion) coefficient)) and ((stacking stacked stack stackable mounting mounted mounting) with (die chip dice ic (integrated adj circuit))))) and (package packaged packaging)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17
. 13	2009	(((epoxy molding encapsulate encapsulation encapsulated) and ((substrate carrier board) and (((heat with (spreader dissipating dissipated dissipate sink metal slug radiate cooling)) and (cte (thermal with expansion) coefficient)) and ((stacking stacked stack stackable mounting mounted mounting) with (die chip dice ic (integrated adj circuit))))) and (package packaged packaging)) not ((substrate carrier board) and ((epoxy molding encapsulate encapsulation encapsulated) and (((stacking stacked stack stackable mounting mounted mounting) with (die chip dice ic (integrated adj circuit))) same ((heat with (spreader sink metal slug radiate cooling)))) and (thermal with expansion))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17
14	467	((stacking stacked stack stackable mounting mounted mounting) with (die chip dice ic (integrated adj circuit))) and ((heat with (spreader dissipating dissipated dissipate sink metal slug radiate cooling))) and 257/777	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17
15	2469		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 10:24
16	2222	257/777	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/03/17 10:24
17	3741	257/686 257/777	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/03/17 10:24
18	786	((stacking stacked stack stackable mounting mounted mounting) with (die chip dice ic (integrated adj circuit))) and ((heat with (spreader dissipating dissipated dissipate sink metal slug radiate cooling))) and (257/686 257/777)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 10:25

			TIGDAM.	1 2004 /02 /17
19	621	(((stacking stacked stack stackable mounting mounted mounting) with (die chip	USPAT; US-PGPUB;	2004/03/17 10:25
		dice ic (integrated adj circuit))) and	EPO; JPO;	
		((heat with (spreader dissipating	DERWENT;	
		dissipated dissipate sink metal slug	IBM TDB	
		radiate cooling))) and (257/686 257/777))	15	
		not ((((epoxy molding encapsulate		
		encapsulation encapsulated) and		
				1
		((substrate carrier board) and (((heat		
		with (spreader dissipating dissipated		
		dissipate sink metal slug radiate		
		cooling))) and (cte (thermal with		
		expansion) coefficient)) and ((stacking		
		stacked stack stackable mounting mounted		1
		mounting) with (die chip dice ic		
		(integrated adj circuit))))) and		
		(package packaged packaging)) not		
		((substrate carrier board) and ((epoxy		
1		molding encapsulate encapsulation		
		encapsulated) and (((stacking stacked		
		stack stackable mounting mounted		
		mounting) with (die chip dice ic		
		(integrated adj circuit))) same ((heat		
		with (spreader sink metal slug radiate		
		cooling)))) and (thermal with		
		expansion)))))		
20	621	(heat with (spreader dissipating	USPAT;	2004/03/17
		dissipated dissipate sink metal slug	US-PGPUB;	10:26
		radiate cooling)) and (((stacking	EPO; JPO;	
		stacked stack stackable mounting mounted	DERWENT;	
		mounting) with (die chip dice ic	IBM TDB	
		(integrated adj circuit))) and ((heat	_	
		with (spreader dissipating dissipated		
		dissipate sink metal slug radiate		
		cooling))) and (257/686 257/777)) not		
		((((epoxy molding encapsulate		1
		encapsulation encapsulated) and		+
		((substrate carrier board) and (((heat		
+		with (spreader dissipating dissipated		
		dissipate sink metal slug radiate		
		cooling))) and (cte (thermal with		
,		expansion) coefficient)) and ((stacking		
		stacked stack stackable mounting mounted		
		mounting) with (die chip dice ic		
1		(integrated adj circuit))))) and		
		I	:	
		(package packaged packaging)) not ((substrate carrier board) and ((epoxy		
		molding encapsulate encapsulation	1	
		encapsulated) and ((((stacking stacked		
		stack stackable mounting mounted		
		mounting) with (die chip dice ic		
		(integrated adj circuit))) same ((heat		
		with (spreader sink metal slug radiate		1
		cooling)))) and (thermal with		
		expansion))))))		